

# FDS7064A

## 30V N-Channel PowerTrench<sup>®</sup> MOSFET

### General Description

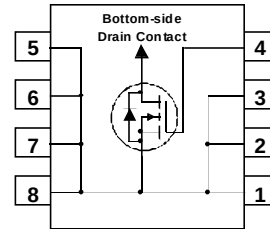
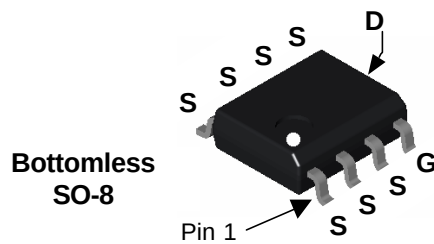
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for "low side" synchronous rectifier operation, providing an extremely low  $R_{DS(ON)}$  in a small package.

### Applications

- Synchronous rectifier
- DC/DC converter

### Features

- 19 A, 30 V  $R_{DS(ON)} = 6.5 \text{ m}\Omega @ V_{GS} = 4.5 \text{ V}$
- High performance trench technology for extremely low  $R_{DS(ON)}$
- High power and current handling capability
- Fast switching
- Bottomless<sup>™</sup> SO-8 package: Enhanced thermal performance in industry-standard package size



### Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

| Symbol         | Parameter                                        | Ratings         | Units            |
|----------------|--------------------------------------------------|-----------------|------------------|
| $V_{DSS}$      | Drain-Source Voltage                             | 30              | V                |
| $V_{GSS}$      | Gate-Source Voltage                              | $\pm 12$        | V                |
| $I_D$          | Drain Current – Continuous (Note 1a)             | 19              | A                |
|                | – Pulsed                                         | 60              |                  |
| $P_D$          | Power Dissipation for Single Operation (Note 1a) | 3.9             | W                |
| $T_J, T_{STG}$ | Operating and Storage Junction Temperature Range | $-55$ to $+175$ | $^\circ\text{C}$ |

### Thermal Characteristics

|                 |                                                   |    |                    |
|-----------------|---------------------------------------------------|----|--------------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (Note 1a) | 38 | $^\circ\text{C/W}$ |
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case              | 1  | $^\circ\text{C/W}$ |

### Package Marking and Ordering Information

| Device Marking | Device   | Reel Size | Tape width | Quantity   |
|----------------|----------|-----------|------------|------------|
| FDS7064A       | FDS7064A | 13"       | 12mm       | 2500 units |

**Electrical Characteristics** $T_A = 25^\circ\text{C}$  unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|
|--------|-----------|-----------------|-----|-----|-----|-------|

**Off Characteristics**

|                                      |                                           |                                                                   |    |    |      |                      |
|--------------------------------------|-------------------------------------------|-------------------------------------------------------------------|----|----|------|----------------------|
| $BV_{DSS}$                           | Drain–Source Breakdown Voltage            | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$               | 30 |    |      | V                    |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$ |    | 20 |      | mV/ $^\circ\text{C}$ |
| $I_{DSS}$                            | Zero Gate Voltage Drain Current           | $V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$                       |    |    | 1    | $\mu\text{A}$        |
| $I_{GSSF}$                           | Gate–Body Leakage, Forward                | $V_{GS} = 12\text{ V}, V_{DS} = 0\text{ V}$                       |    |    | 100  | nA                   |
| $I_{GSSR}$                           | Gate–Body Leakage, Reverse                | $V_{GS} = -12\text{ V}, V_{DS} = 0\text{ V}$                      |    |    | -100 | nA                   |

**On Characteristics** (Note 2)

|                                        |                                                |                                                                                         |     |     |            |                      |
|----------------------------------------|------------------------------------------------|-----------------------------------------------------------------------------------------|-----|-----|------------|----------------------|
| $V_{GS(th)}$                           | Gate Threshold Voltage                         | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$                                         | 0.8 | 1.2 | 2          | V                    |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate Threshold Voltage Temperature Coefficient | $I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$                       |     | -4  |            | mV/ $^\circ\text{C}$ |
| $R_{DS(on)}$                           | Static Drain–Source On–Resistance              | $V_{GS} = 4.5\text{ V}, I_D = 19\text{ A}$<br>$V_{GS} = 10\text{ V}, I_D = 21\text{ A}$ |     |     | 6.5<br>5.5 | m $\Omega$           |
| $I_{D(on)}$                            | On–State Drain Current                         | $V_{GS} = 4.5\text{ V}, V_{DS} = 5\text{ V}$                                            | 50  |     |            | A                    |
| $g_{FS}$                               | Forward Transconductance                       | $V_{DS} = 10\text{ V}, I_D = 19\text{ A}$                                               |     | 75  |            | S                    |

**Dynamic Characteristics**

|           |                              |                                                                      |  |      |  |    |
|-----------|------------------------------|----------------------------------------------------------------------|--|------|--|----|
| $C_{iss}$ | Input Capacitance            | $V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V},$<br>$f = 1.0\text{ MHz}$ |  | 5070 |  | pF |
| $C_{oss}$ | Output Capacitance           |                                                                      |  | 550  |  | pF |
| $C_{rss}$ | Reverse Transfer Capacitance |                                                                      |  | 230  |  | pF |

**Switching Characteristics** (Note 2)

|              |                     |                                                                                                 |  |     |     |    |
|--------------|---------------------|-------------------------------------------------------------------------------------------------|--|-----|-----|----|
| $t_{d(on)}$  | Turn–On Delay Time  | $V_{DD} = 10\text{ V}, I_D = 1\text{ A},$<br>$V_{GS} = 4.5\text{ V}, R_{GEN} = 6\text{ }\Omega$ |  | 17  | 25  | ns |
| $t_r$        | Turn–On Rise Time   |                                                                                                 |  | 18  | 25  | ns |
| $t_{d(off)}$ | Turn–Off Delay Time |                                                                                                 |  | 69  | 100 | ns |
| $t_f$        | Turn–Off Fall Time  |                                                                                                 |  | 29  | 42  | ns |
| $Q_g$        | Total Gate Charge   | $V_{DS} = 15\text{ V}, I_D = 19\text{ A},$<br>$V_{GS} = 4.5\text{ V}$                           |  | 33  | 46  | nC |
| $Q_{gs}$     | Gate–Source Charge  |                                                                                                 |  | 7.5 |     | nC |
| $Q_{gd}$     | Gate–Drain Charge   |                                                                                                 |  | 6.8 |     | nC |

**Drain–Source Diode Characteristics and Maximum Ratings**

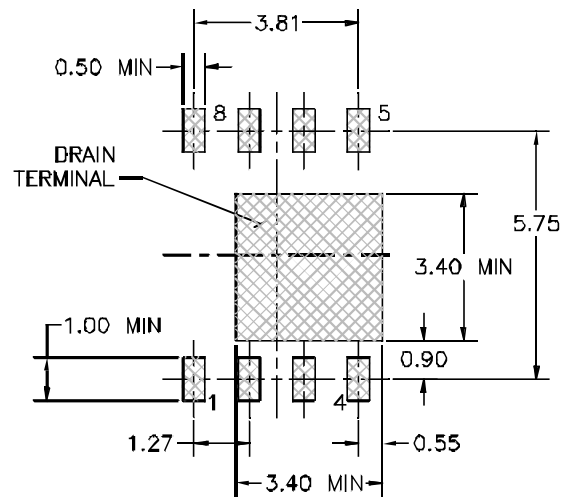
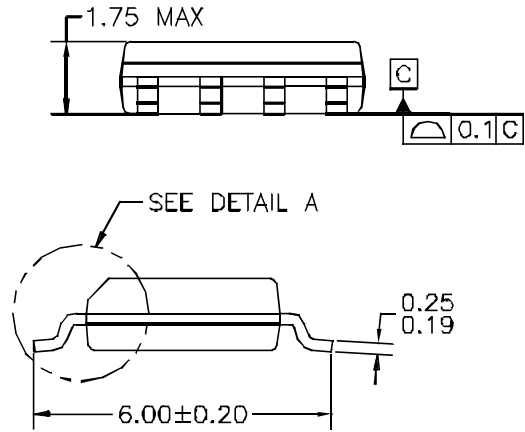
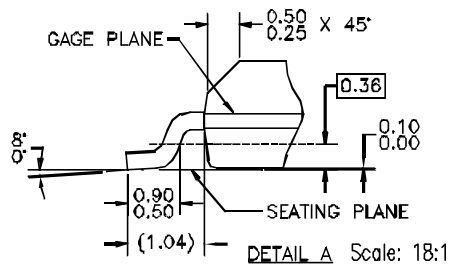
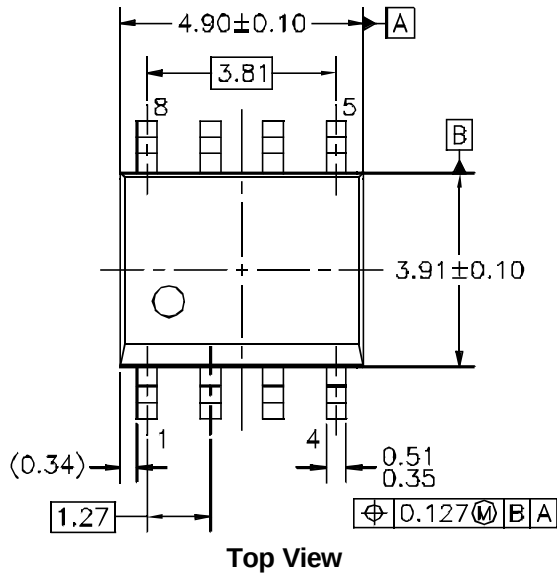
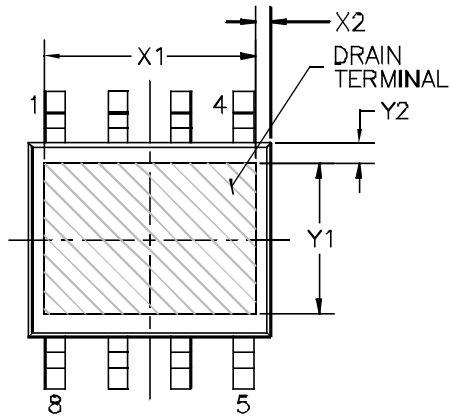
|          |                                                       |                                                    |  |  |     |   |
|----------|-------------------------------------------------------|----------------------------------------------------|--|--|-----|---|
| $I_S$    | Maximum Continuous Drain–Source Diode Forward Current |                                                    |  |  | 3.2 | A |
| $V_{SD}$ | Drain–Source Diode Forward Voltage                    | $V_{GS} = 0\text{ V}, I_S = 3.2\text{ A}$ (Note 2) |  |  | 1.2 | V |

**Notes:**

1.  $R_{\theta JA}$  is the junction-to-ambient thermal resistance.  $R_{\theta JA}$  depends on the user's board design.

a)  $38^\circ\text{C/W}$  when mounted on a  $1\text{ in}^2$  pad of 2 oz copper

# Dimensional Outline and Pad Layout



## Notes Unless otherwise Specified

- All dimensions in mm
- Standard lead finish:  
20 – 80  $\mu$  inches nickel /  
6  $\mu$  inches palladium
- Chip Size Dimensional Table

| Chip Size |      | X2   | Y2   |
|-----------|------|------|------|
| X1        | Y1   |      |      |
| 2.36      | 2.36 | 0.75 | 0.67 |

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